

US00D864883S

(12) **United States Design Patent**  
**Sakamoto**

(10) **Patent No.:** **US D864,883 S**

(45) **Date of Patent:** **\*\* \*Oct. 29, 2019**

(54) **PART FOR SEMICONDUCTOR DEVICE**

(56) **References Cited**

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(73) Assignee: **HAMAMATSU PHOTONICS K.K.**,  
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(\*) Notice: This patent is subject to a terminal disclaimer.

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(Continued)

(\*\*) Term: **15 Years**

*Primary Examiner* — Elizabeth J Oswecki

(21) Appl. No.: **29/641,840**

(74) *Attorney, Agent, or Firm* — Drinker Biddle & Reath  
LLP

(22) Filed: **Mar. 26, 2018**

(57) **CLAIM**

The ornamental design for a part for semiconductor device,  
as shown and described.

(30) **Foreign Application Priority Data**

Sep. 27, 2017 (JP) ..... 2017-021144

(51) **LOC (12) Cl.** ..... **13-03**

(52) **U.S. Cl.**

USPC ..... **D13/182**

(58) **Field of Classification Search**

USPC ..... D13/110, 182; 257/678, 684, 690, 691;  
361/679.01, 713, 728, 736, 760, 761, 772,  
361/775, 783, 820; 174/250, 253;  
438/15, 25, 26, 51, 55, 63, 64, 106

CPC . H01L 21/00; H01L 2224/42; H01L 2224/43;  
H01L 2021/00; H01L 2021/02; H01L  
2021/04; H01L 21/4814; H01L 21/4846;  
H01L 21/4871; H01L 21/67144; H01L  
23/12; H01L 23/13; H01L 23/14; H01L  
23/147; H01L 2924/171; H01L  
2924/1711; H01L 2924/1715; H01L  
2924/171151; H01L 2924/181; H01L  
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2924/19042; H01L 2224/08054; H01L  
23/58; H05B 41/14; H05K 1/142; H05K

(Continued)

**DESCRIPTION**

FIG. 1 is a front view of a part for semiconductor device  
showing my new design;

FIG. 2 is a rear view thereof;

FIG. 3 is a top plan view thereof;

FIG. 4 is a bottom plan view thereof;

FIG. 5 is a right side view thereof;

FIG. 6 is a left side view thereof;

FIG. 7 is a perspective view thereof;

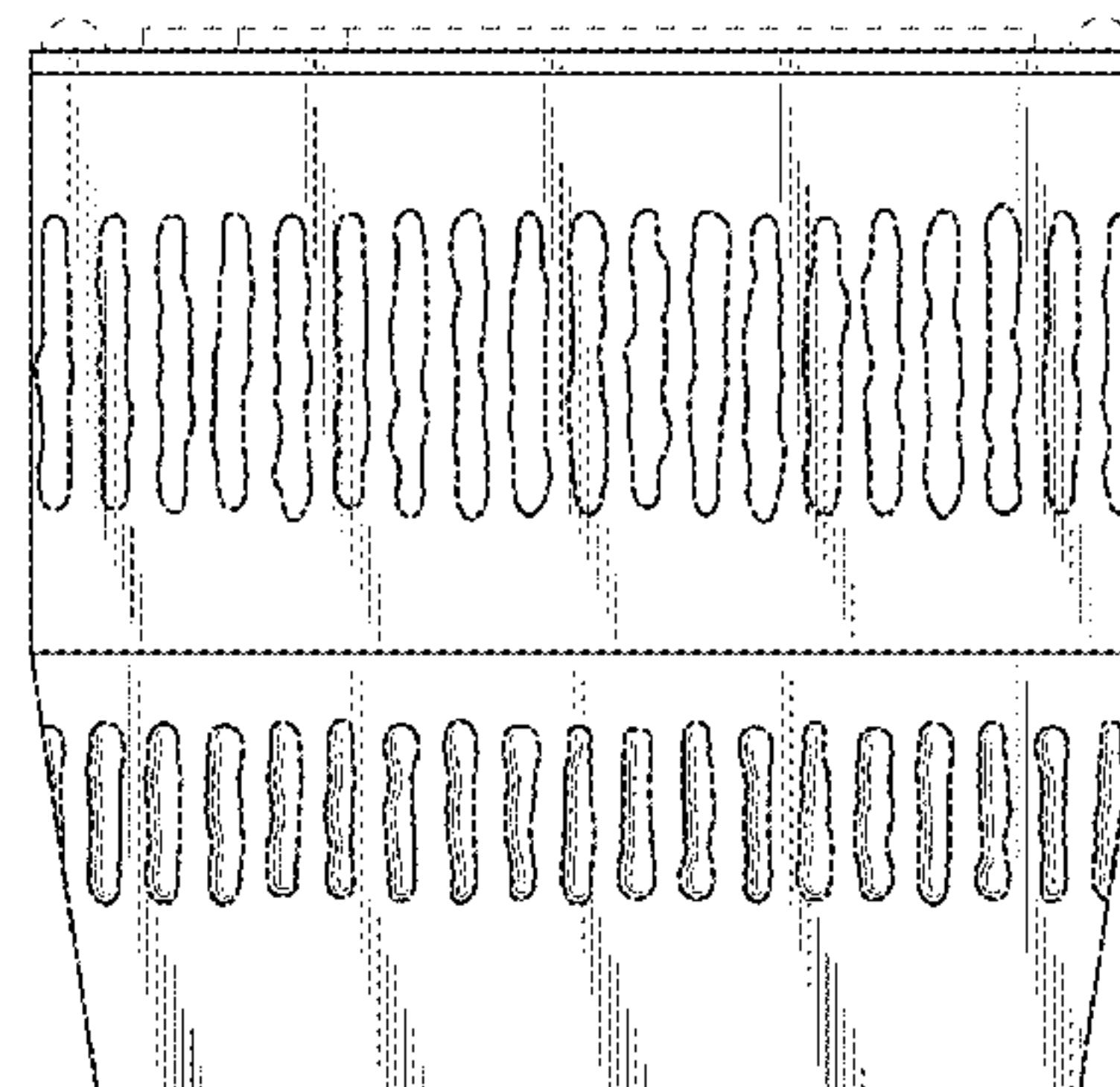
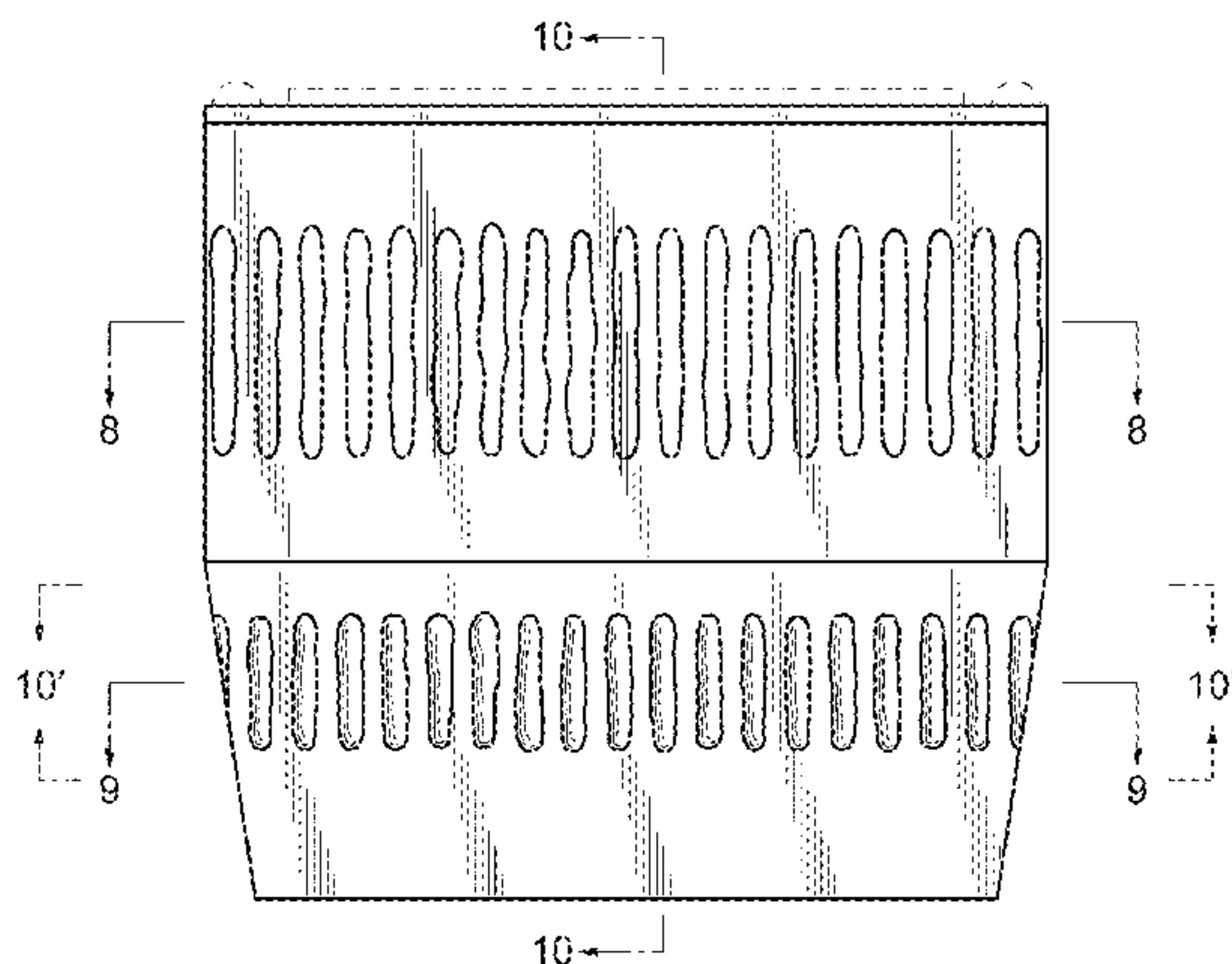
FIG. 8 is an enlarged cross-sectional view taken along line  
**8-8** in FIG. 1;

FIG. 9 is an enlarged cross-sectional view taken along line  
**9-9** in FIG. 1; and,

FIG. 10 is an enlarged cross-sectional view of a portion  
labeled **10'-10'** in FIG. 1 and a portion labeled **10"-10"** in  
FIG. 5 taken along line **10-10** in FIG. 1.

The features shown in broken lines depict environmental  
subject matter only and form no part of the claimed design.

**1 Claim, 10 Drawing Sheets**



(58) **Field of Classification Search**  
 CPC ..... 1/144; H05K 1/18; H05K 1/181; H05K  
 1/182; H05K 1/026  
 See application file for complete search history.

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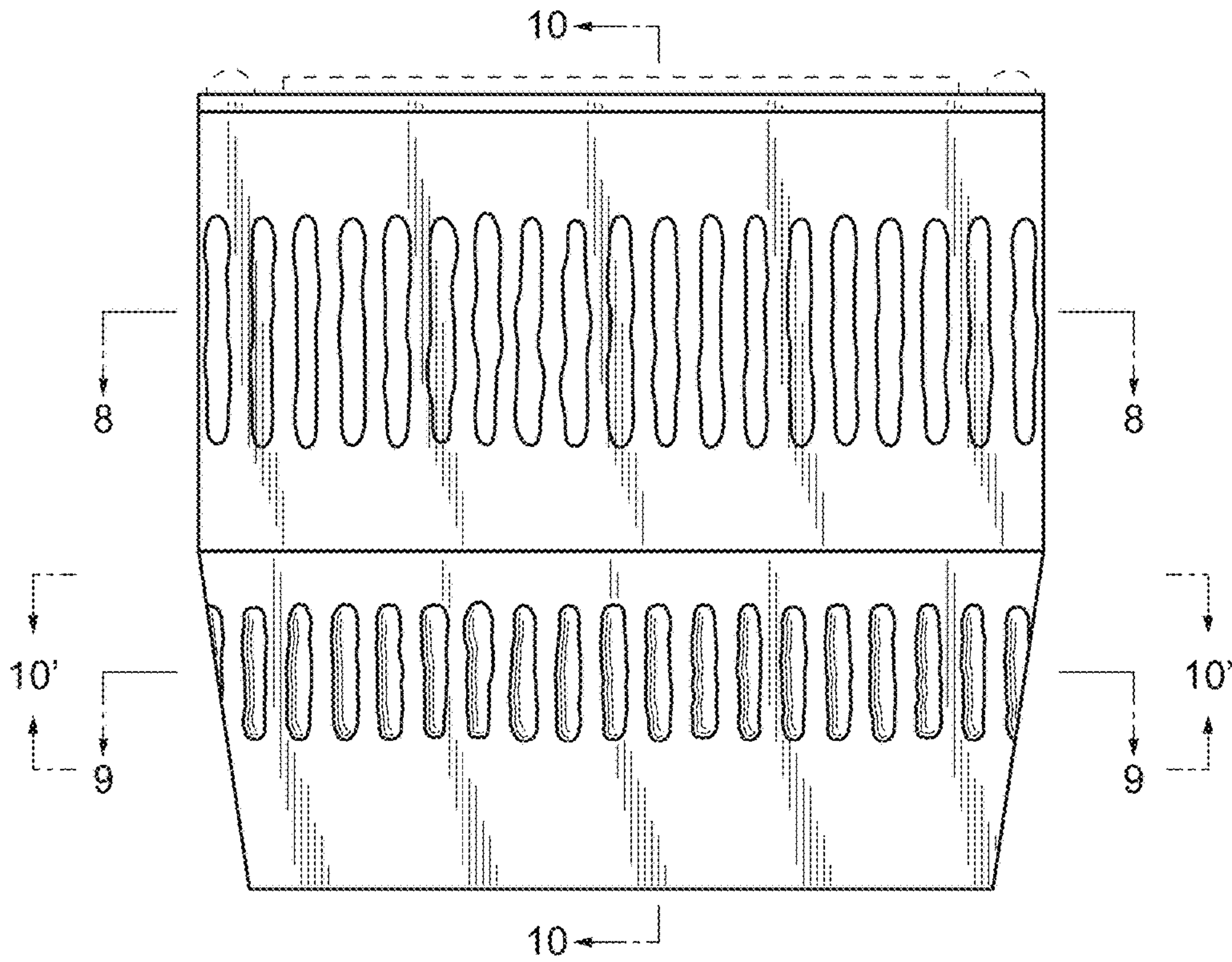


FIG. 1



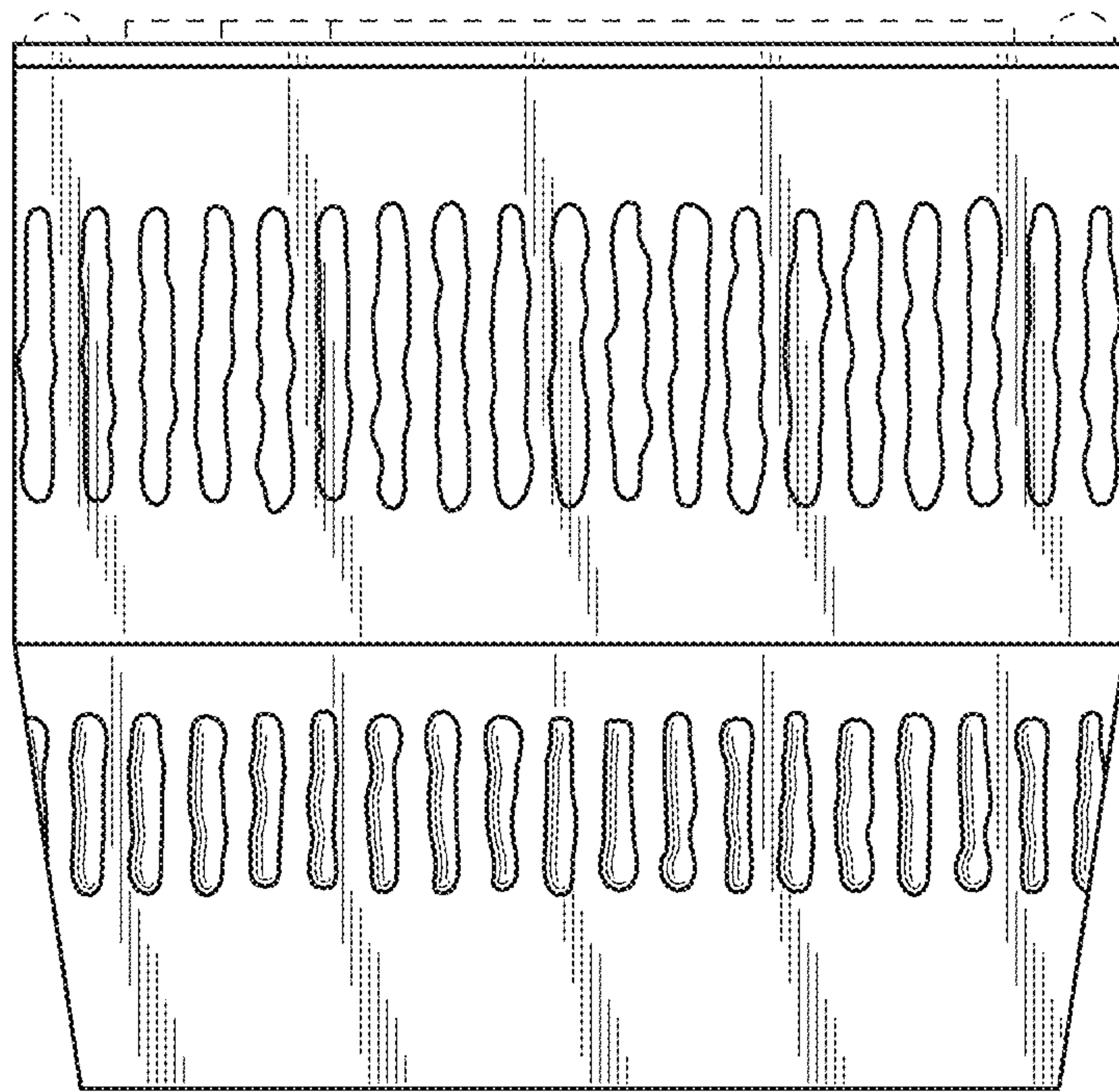


FIG. 2

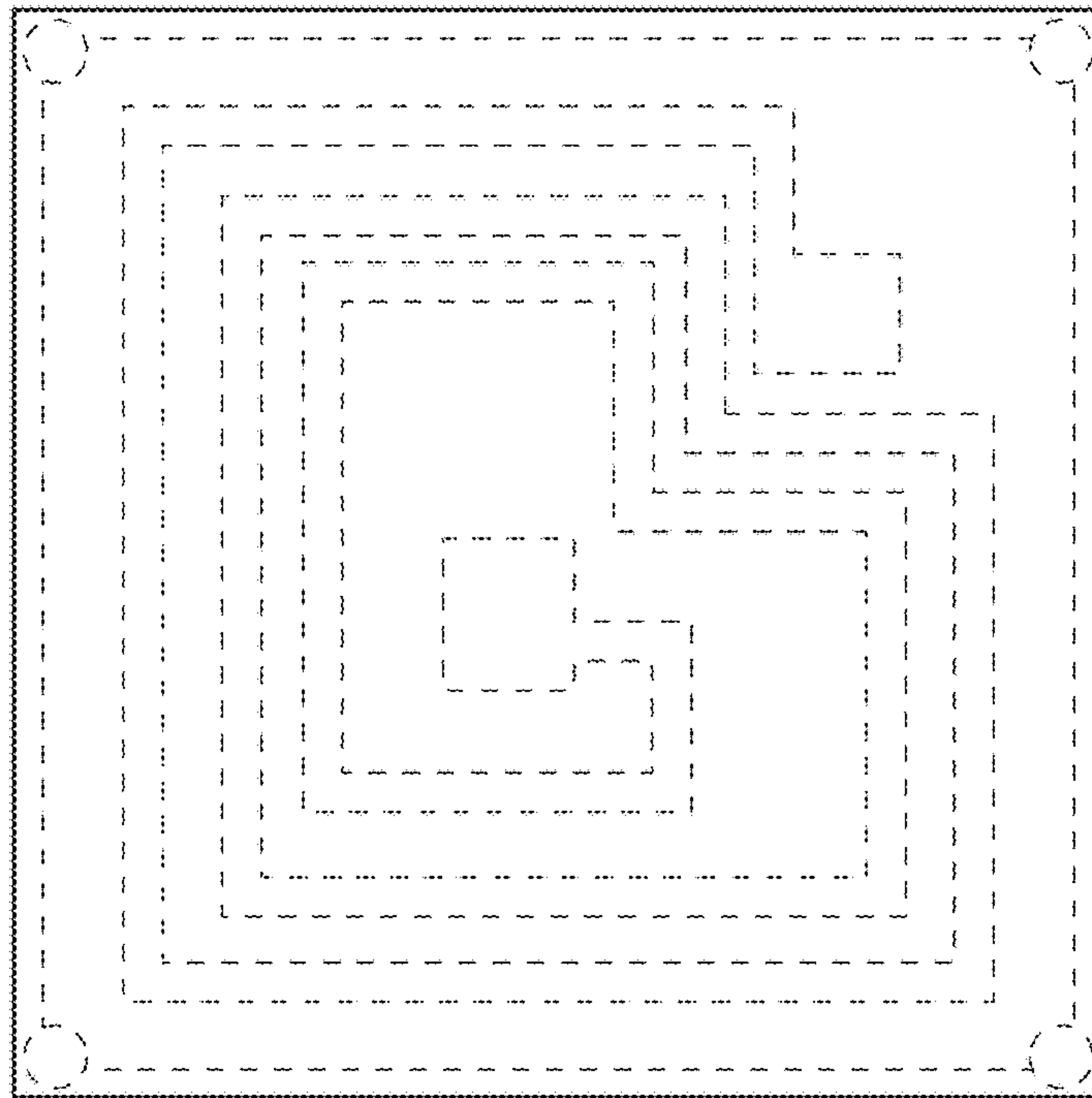


FIG. 3

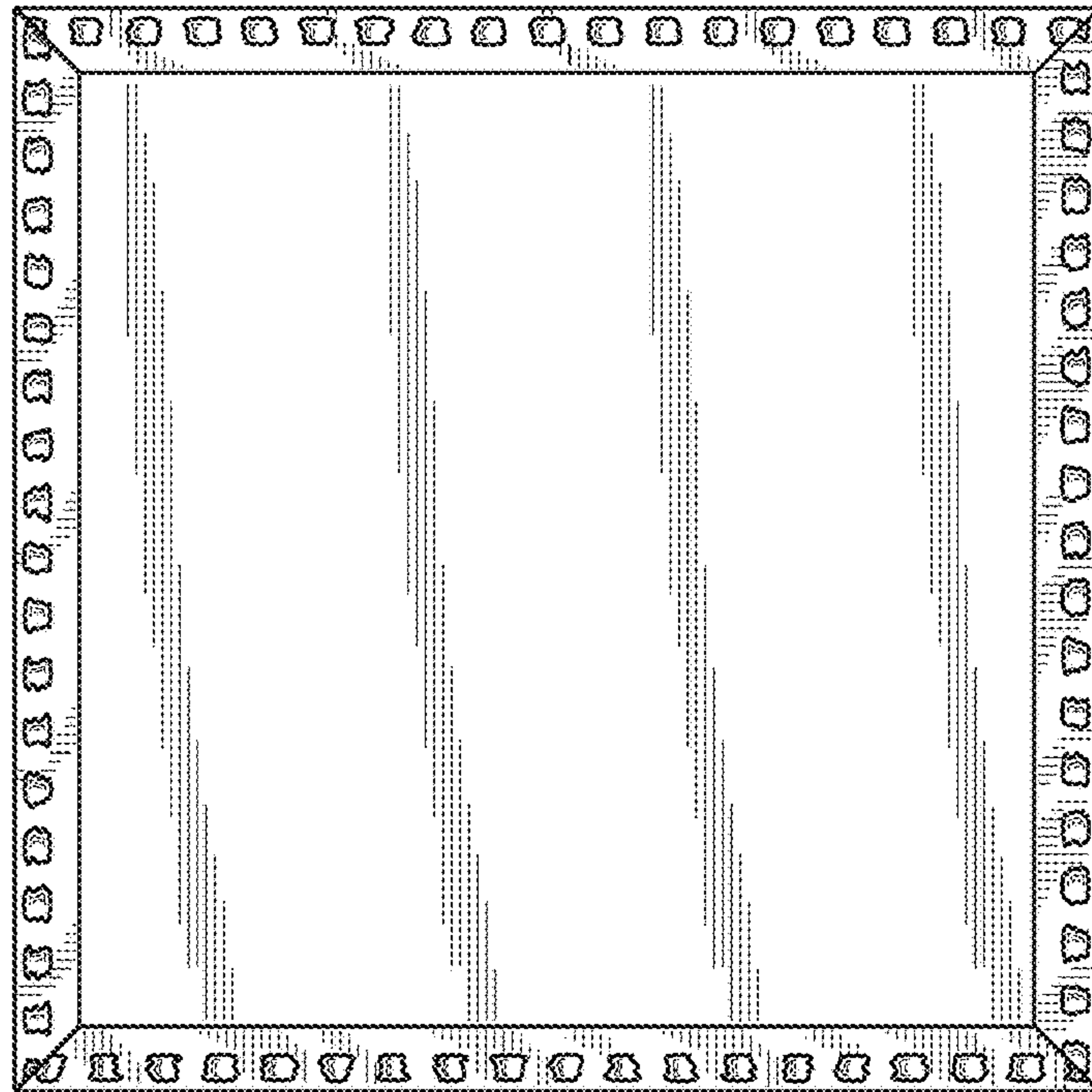


FIG. 4

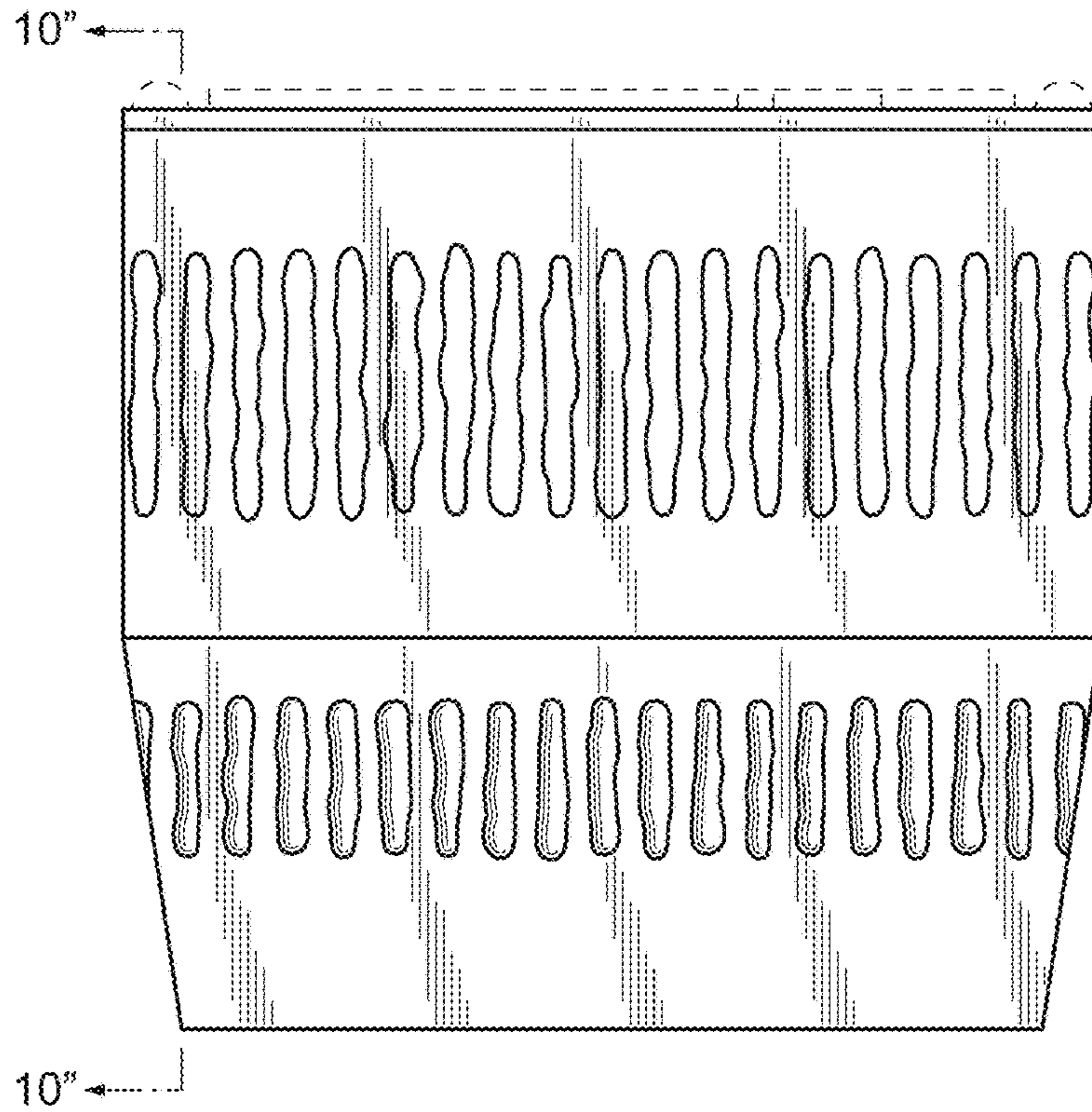


FIG. 5

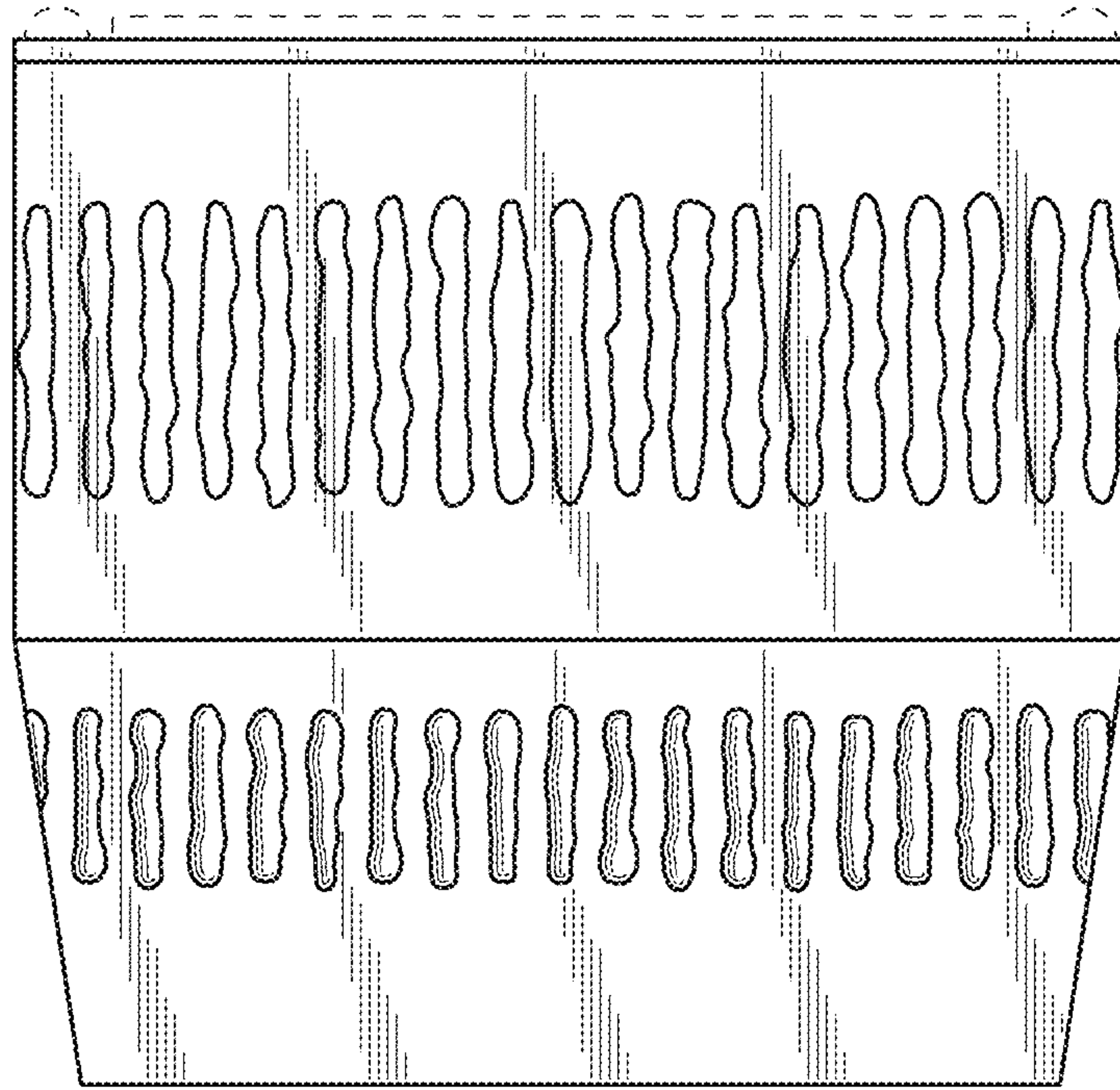


FIG. 6



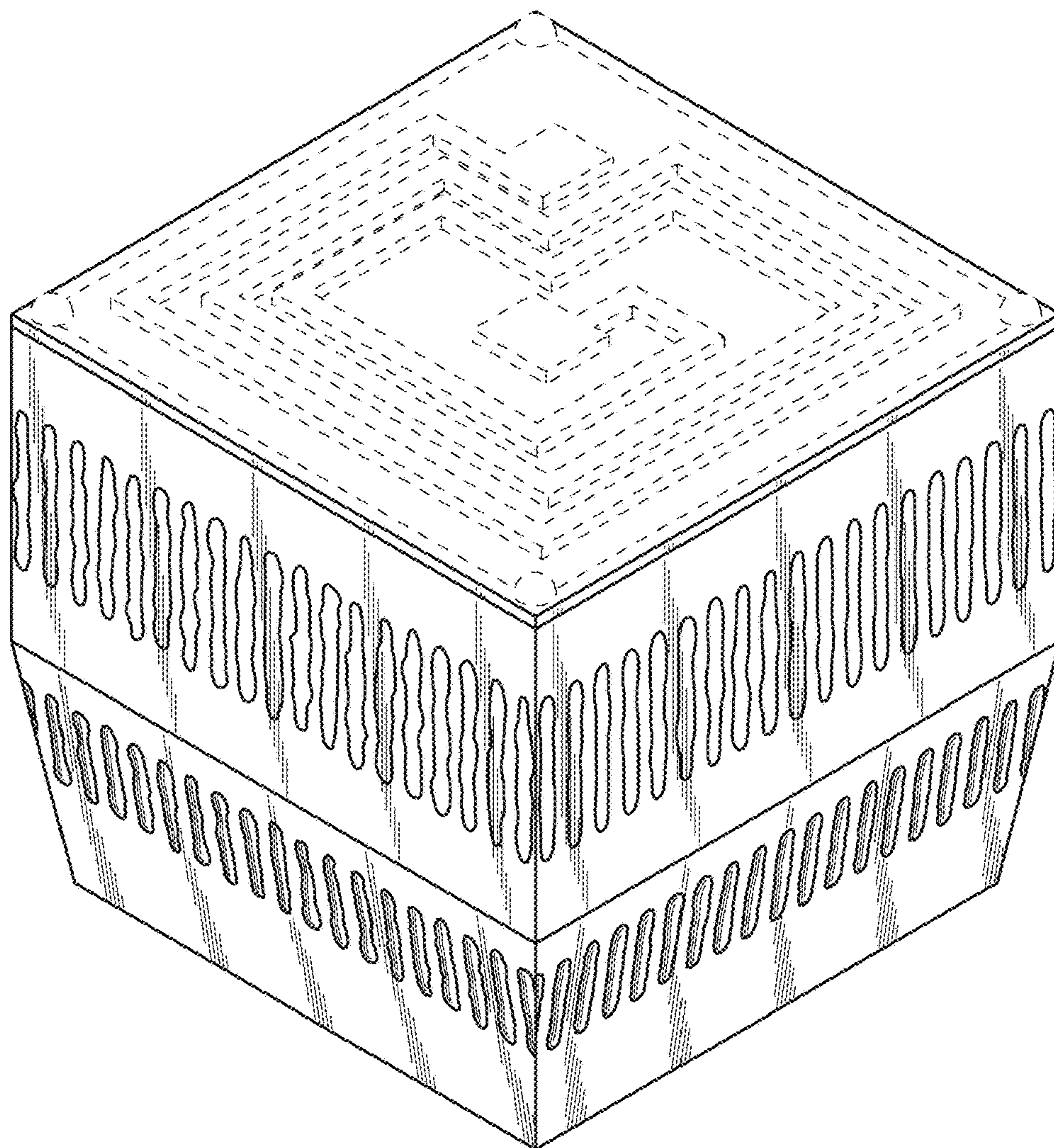


FIG. 7

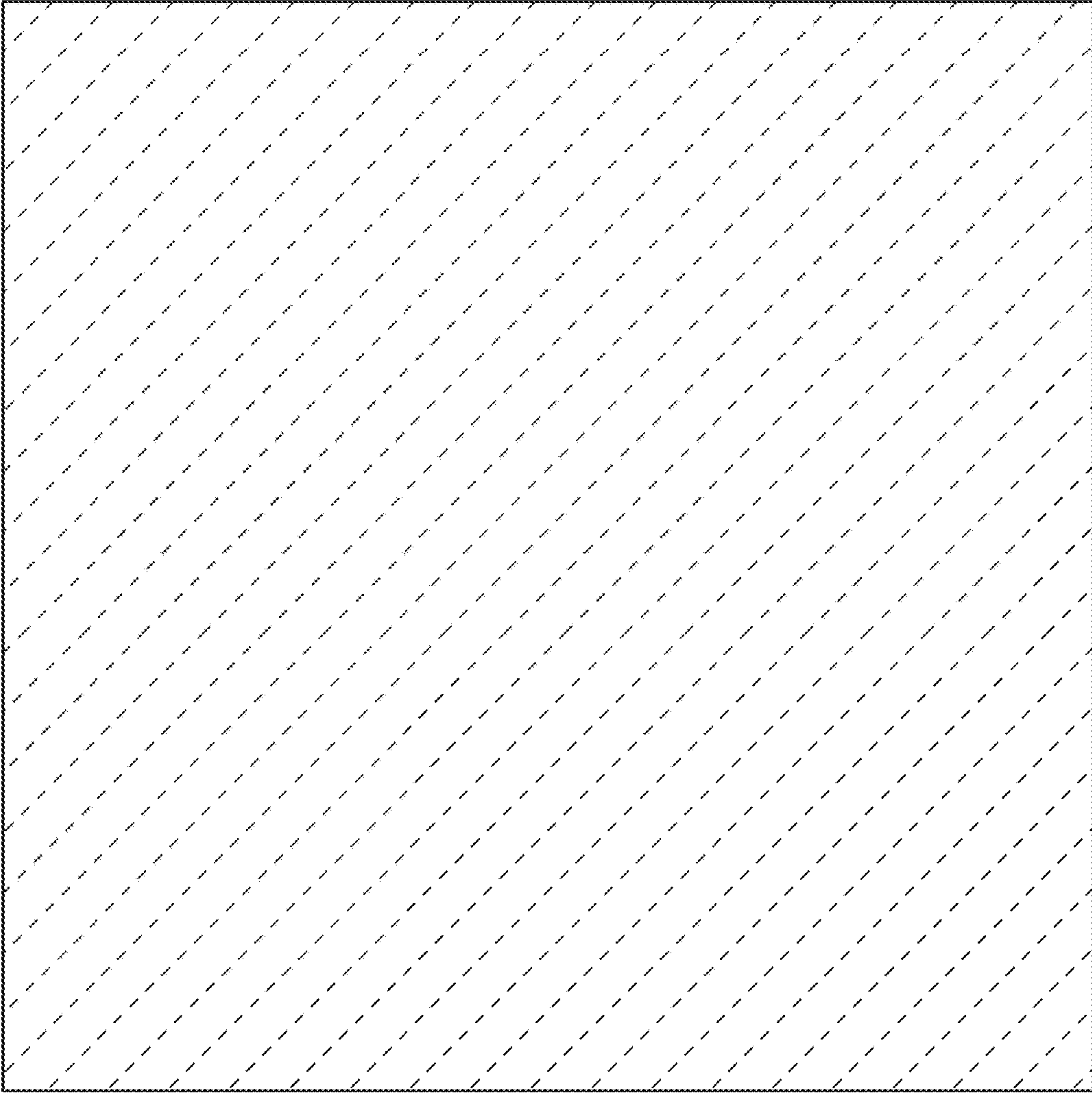


FIG. 8

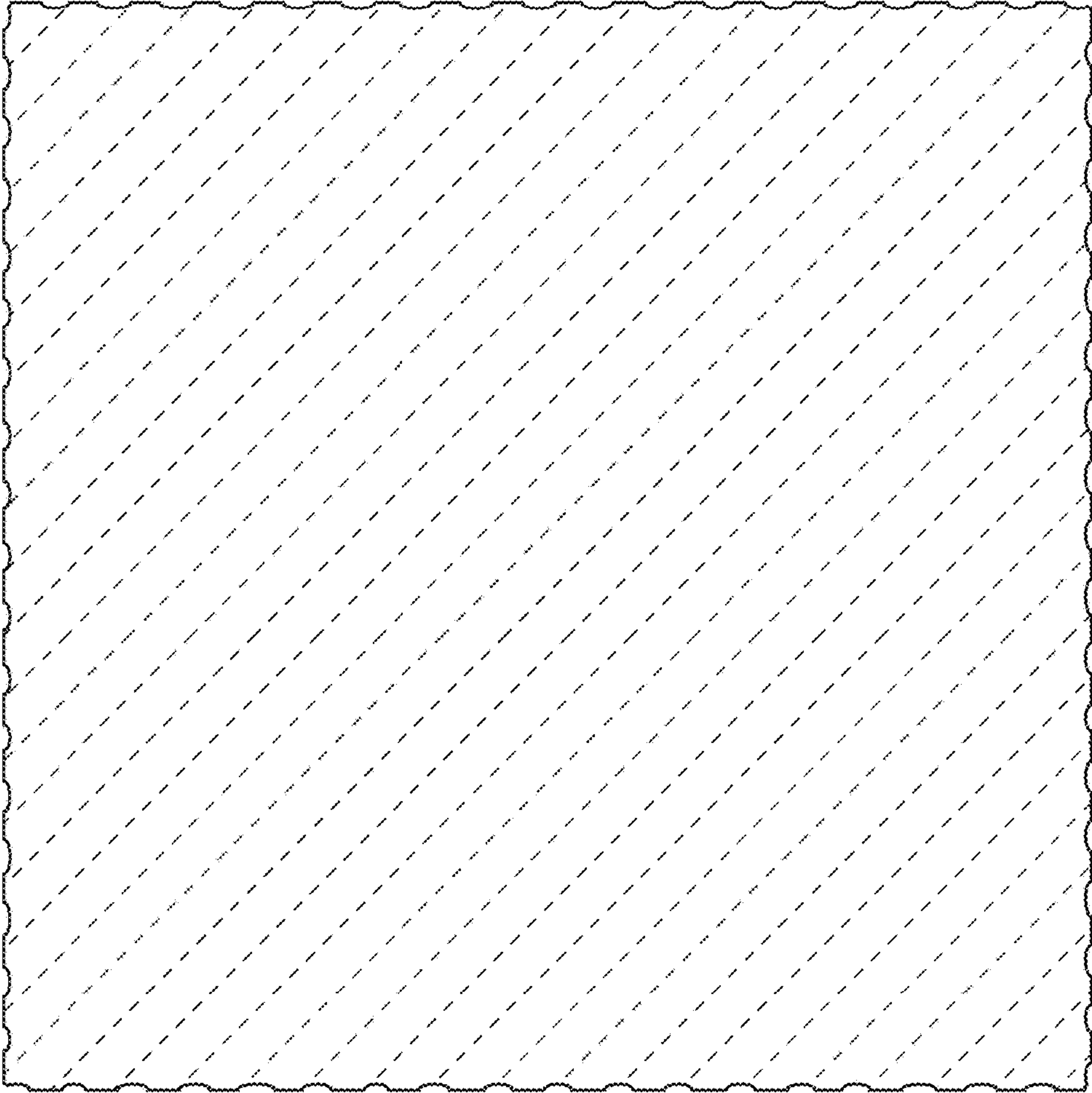


FIG. 9

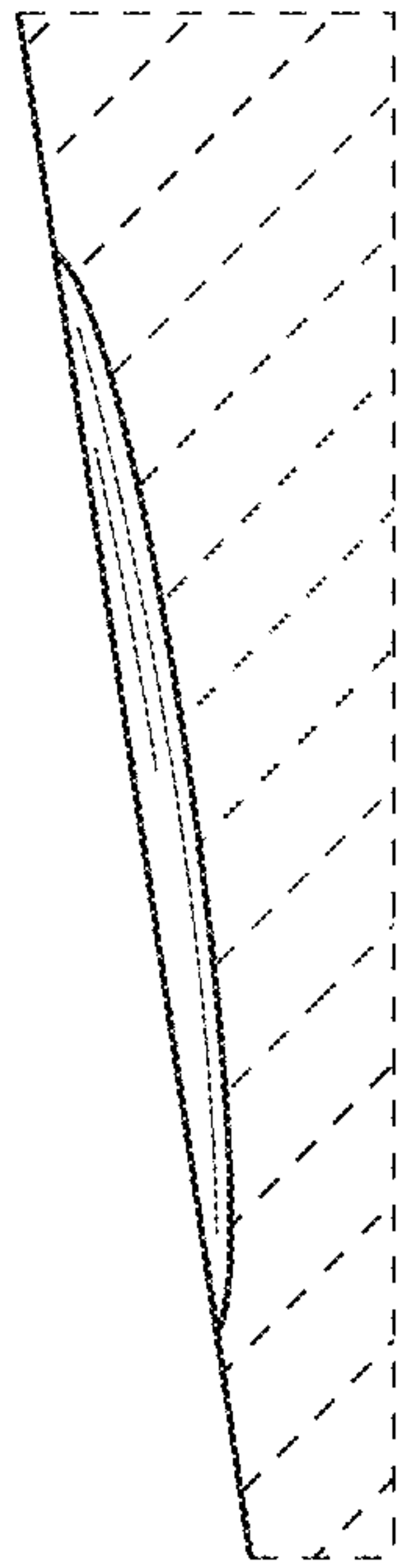


FIG. 10